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PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2748165

SUBMISSION TYPE: NEW ASSIGNMENT			
NATURE OF CONVEYANCE:	ASSIGNMENT		
CONVEYING PARTY DATA			
Name		Execution Date	
CHIN-SHENG CHEN		02/10/2014	

WEI-YI HU 02/10/2014 JUI-FENG KUAN 02/10/2014		
JUI-FENG KUAN 02/10/2014	WEI-YI HU	02/10/2014
	JUI-FENG KUAN	02/10/2014

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14193563

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	T5057-890A	
NAME OF SUBMITTER:	RANDY A. NORANBROCK	
Signature:	/Randy A. Noranbrock/	
Date:	02/28/2014	

Total Attachments: 1

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PATENT REEL: 032324 FRAME: 0438

Docket No. T5057-890A TSMC2013-0241

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Jaw-Juinn HORNG
- 2) Szu-Lin LIU

RECORDED: 02/28/2014

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3) Chung-Hui CHEN

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.				
	cessors and assigns (hereinafter designated "ASSIGNEE") the enti ned in 35 U.S.C. 100 in the invention entitled	re right, title and interest for the United States of America		
(a)	for which an application for United States Letters Patent was fil- United States Patent Application No.	ed on, and identified by; or		
(b)	for which an application for United States Letters Patent was ex	ecuted on,		
all Uni continu Proper	e undersigned hereby authorizes and requests the United States Cited States Letters Patent which may be granted therefore and any unations-in-part thereof, and the right to all benefits under the It to the said ASSIGNEE, for its interest as ASSIGNEE, its succethat the attorneys of record in said application shall hereafter act or	y and all extensions, divisions, reissues, continuations, or nternational Convention for the Protection of Industrial essors, assigns and legal representatives; the undersigned n behalf of said ASSIGNEE;		
AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.				
SIGNED on the date indicated aside my signature:				
I) Nam	e: Jaw-Juinn MORNG	つい (, ン , / O Date:		
2) Nam	Szu Lin LIU	2014 . 2 . 1 ° Date:		
3)	Clar, Chuy Uw e: Chung-Hui CHEN	Date:		

PATENT REEL: 032324 FRAME: 0439